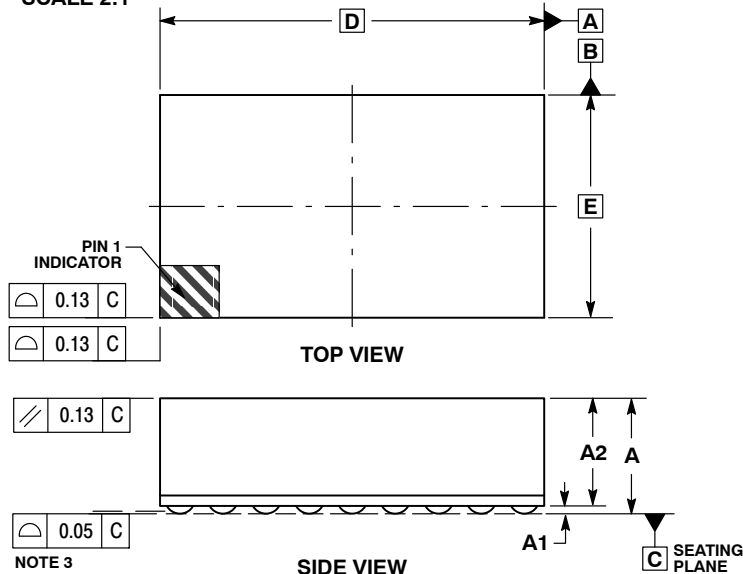

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ISSUE O

DATE 12 APR 2016

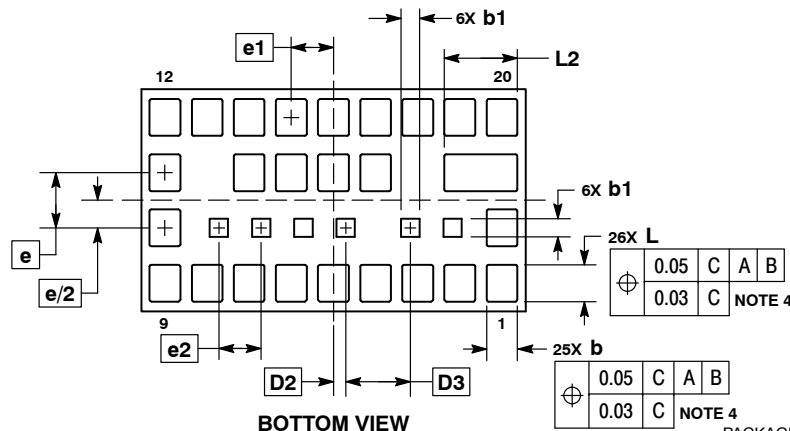
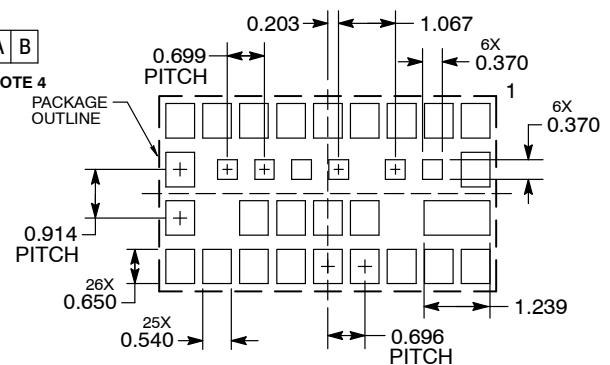
SCALE 2:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BUMPS.
4. DIMENSIONS b, b1, L AND L2 ARE MEASURED AT THE MAXIMUM BUMP DIMENSION PARALLEL TO DATUM C. THE POSITIONAL TOLERANCE APPLIES TO ALL OF THE SOLDER BUMPS.

DIM	MILLIMETERS	
	MIN	MAX
A		1.960
A1	0.076	0.180
A2		1.780
b	0.478	0.538
b1	0.275	0.335
D	6.350	BSC
D2	0.203	BSC
D3	1.067	BSC
E	3.683	BSC
e	0.914	BSC
e1	0.696	BSC
e2	0.699	BSC
L	0.580	0.640
L2	1.177	1.237


RECOMMENDED SOLDERING FOOTPRINT*


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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